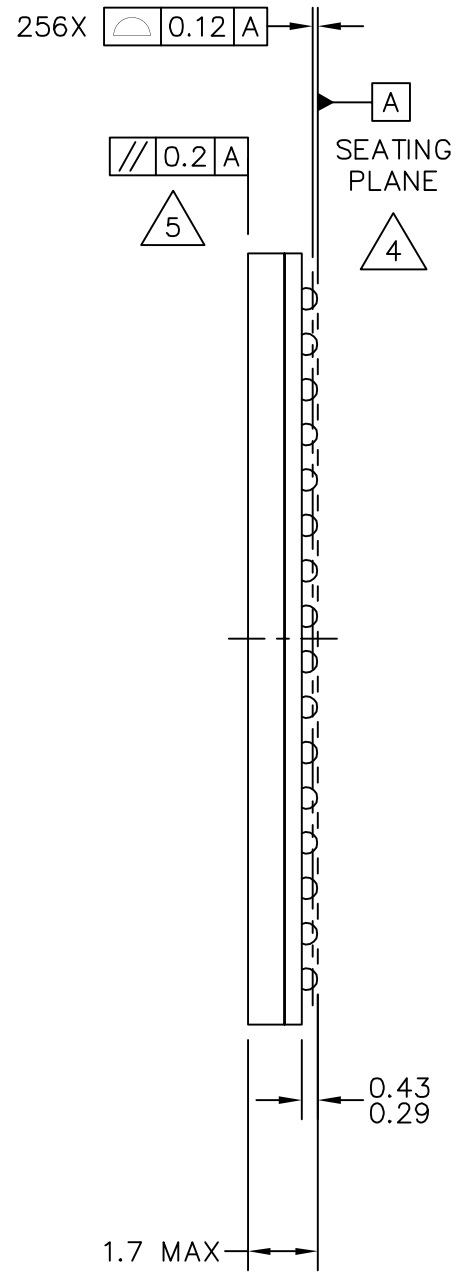
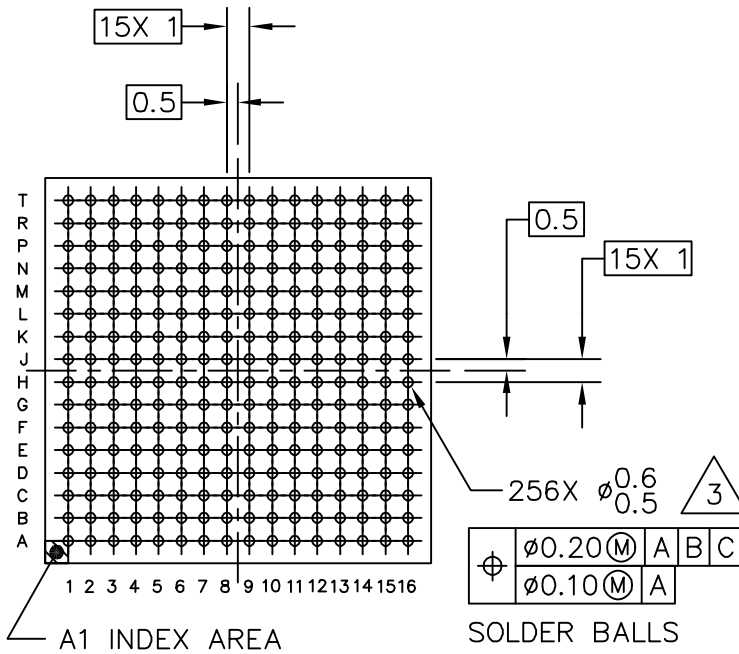


TOP VIEW



SIDE VIEW



BOTTOM VIEW

<p>© FREESCALE SEMICONDUCTOR, INC. ALL RIGHTS RESERVED.</p>	<p>MECHANICAL OUTLINE</p>	<p>PRINT VERSION NOT TO SCALE</p>	
<p>TITLE: MAPPBGA, LOW PROFILE, 256 I/O, 17 X 17 X 1.7 PKG, 1 MM PITCH</p>	<p>DOCUMENT NO: 98ASA00346D</p>	<p>REV: 0</p>	
	<p>CASE NUMBER: 2205-01</p>	<p>31 MAR 2011</p>	
	<p>STANDARD: NON-JEDEC</p>		

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.

2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.

3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.

4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

© FREESCALE SEMICONDUCTOR, INC. ALL RIGHTS RESERVED.	MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE	
TITLE: MAPBGA, LOW PROFILE, 256 I/O, 17 X 17 X 1.7 PKG, 1 MM PITCH	DOCUMENT NO: 98ASA00346D	REV: 0	
	CASE NUMBER: 2205-01	31 MAR 2011	
	STANDARD: NON-JEDEC		